

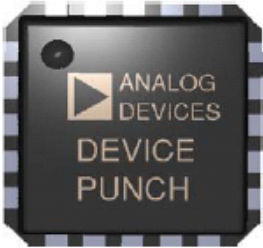

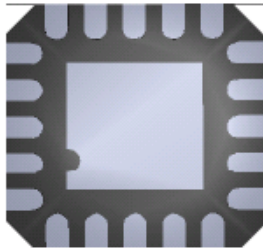
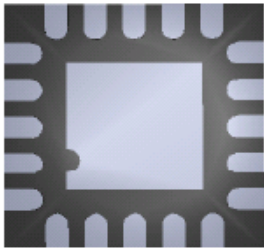
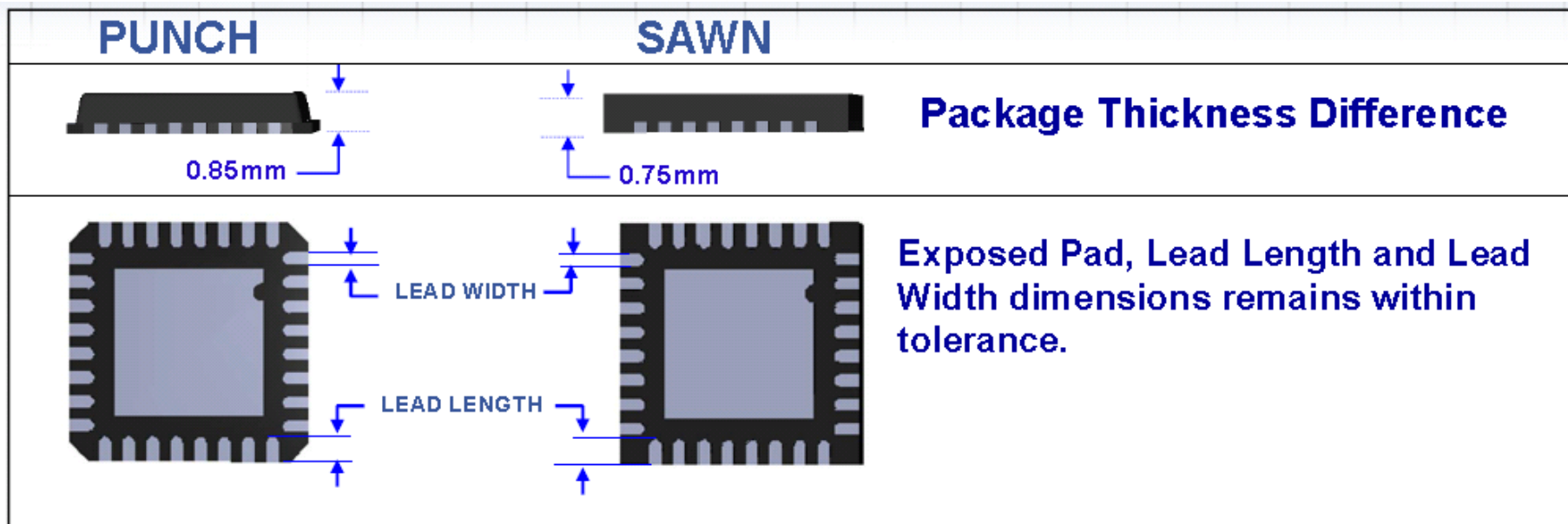


# Bill of Materials and Package Configuration

Material	FROM	TO	Remarks
	Amkor - Korea	Amkor - Philippines	
Die Attach	Ablestik 8290	Ablestik 3230	Same Resin Base
Wire	Au	Au	Same
Mold Compound	Sumitomo G700	Sumitomo G700	Same
Leadframe	C194	C194	Same
<b>Package:</b> Side			<b>Punch:</b> Flange <b>Sawn:</b> Square
Top			<b>Sawn:</b> <ul style="list-style-type: none"> <li>• Pin 1 is Laser Marked</li> <li>• Square Edge</li> </ul>
Bottom			Same Foot Print

# Package Dimensions



Body Size (mm)	Lead Count	Lead Pitch (mm)	Punch LFCSP POD	Sawn LFCSP POD	Exposed Pad Size (mm)
5 x 5	16	0.8	CP 16-6	CP 16-31	3.1 x 3.1
	20	0.65	CP 20-5	CP 20-9	3.1 x 3.1
	32	0.5	CP 32-8	CP 32-21	2.7 x 2.7
			CP 32-2	CP 32-7	3.1 x 3.1
			CP 32-3	CP 32-13	3.3 x 3.3
			CP 32-4	CP 32-11	3.5 x 3.5

# Qualification Results Summary of Sawn LFCSP Package at Amkor Philippines (ATP)

QUALIFICATION RESULTS			
Test	Conditions	Sample Size	Results
Temperature/Humidity Biase (THB)*	JEDEC JESD22-A101	3 x 77	Passed
Temperature Cycle (TC)*	JEDEC JESD22-A104	3 x 77	Passed
Autoclave (AC)*	JEDEC JESD22-A102	3 x 77	Passed
Solder Heat Resistance (SHR)*	JEDEC/IPC J-STD-020	3 x 11	Passed
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	3 x 77	Passed
Field-Induced Charged Device Model (FICDM)	JEDEC JESD22-C101	1 x 18	Passed

\* These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples were subjected to wire-pull test after 500 cycles with results within specification limits.